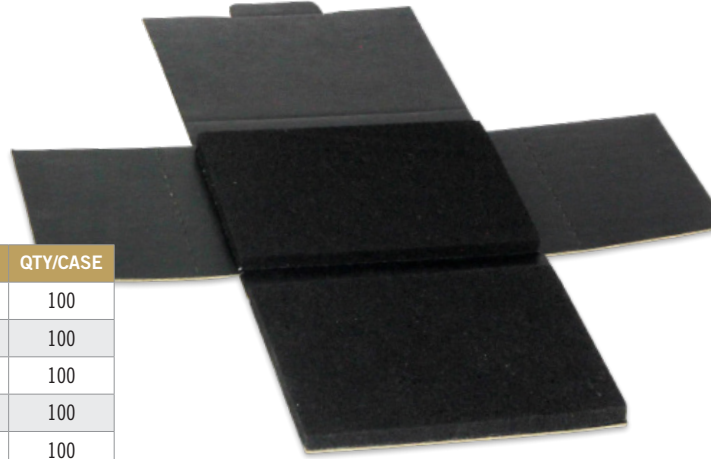




CORSTAT® PILLOWSTAT FOLDERS



- Form-fit cushioning protection
- Permanently ESD safe conductive foam
- No tooling is required
- Corstat® static shielding outer material

PN	L X W X H (D)	QTY/CASE
PPF2525	2-9/16X2-9/16X1/2"	100
PPF3515	3-1/2X1-1/2X1/2"	100
PPF2535	3-1/2X2-9/16X1/2"	100
PPF3545	4-5/8X3-1/2X1/2"	100
PPF7035	7X3-1/2X1/2"	100

SPECIFICATIONS

These products meet and/or exceed ANSI/ESD S20.20-2021 and ANSI/ESD S541-2019.

CORSTAT®		
PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Black	Visual
Surface Resistance		
Burried Shielding-layer Ohms	10 ² -10 ³ Ohms/sq	ANSI/ESD STM11.11-2022
Outer Dissipative-layer Ohms	10 ⁴ -10 ⁵ Ohms/sq	ANSI/ESD STM11.11-2022
Electrostatic Decay Rate	Avg. 0.01 sec	EIA-541
ESD Shielding	Avg. 16.49nJ	Capacitive Probe Test
Reducible Sulphur	.00035%	TAPPI-406

PILLOWSTAT FOAM		
PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Black	Visual
Volume Resistance	10 ³ -10 ⁵ Ohms/sq	ANSI/ESD STM11.12-2021
Surface Resistance	10 ³ -10 ⁵ Ohms/sq	ANSI/ESD STM11.11-2022
Static Decay Rate	0.01 Sec	ASTM D-257
Density	4.8 - 5.2 lbs/ft ³	ASTM D-3574-01
Indent Force Deflection @ 25%	7-17 psi	ASTM D-3574-01
Shelf Life	Long Term	

All values are for pre-formed materials. Electrical values will vary with each individual design. All information, recommendations and suggestions appearing in this bulletin concerning the use of our products are based upon tests and data believed to be reliable; however, it is the user's responsibility to determine the suitability for their own use of the products described herein. Since the actual use by others is beyond our control, no guarantee, expressed or implied, is made by Conductive Containers, Inc. as to the effects of such use or the results to be obtained, nor does Conductive Containers, Inc. assume any liability arising out of use, by others, of the products referred to herein. Nor is the information herein to be construed as absolutely complete since additional information may be necessary or desirable, when particular or exceptional conditions or circumstances exist or because of applicable laws or government regulations. Nothing herein contained is to be construed as permission or as a recommendation to infringe any patent.

